

TITLE:
POLISHING APPARATUS

ABSTRACT

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A technique that can curb occurrence of clogging in a flow channel due to a polishing solution remaining in the flow channel and detect occurrence of clogging when clogging has occurred in the flow channel is provided. A polishing apparatus 1 includes a control device 90. The control device 90 performs: a cleaning process of causing a cleaning solution to flow in a flow channel 70a and then causing a polishing solution to flow in the flow channel 70a when the number of substrates Wf polished by a polishing machine 10 reaches a predetermined number; and a clogging detecting process of detecting whether clogging has occurred in the flow channel based on a pressure or a flow rate of the cleaning solution detected by sensors 60 and 61 when the cleaning solution flows in the flow channel.

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[FIG. 1]